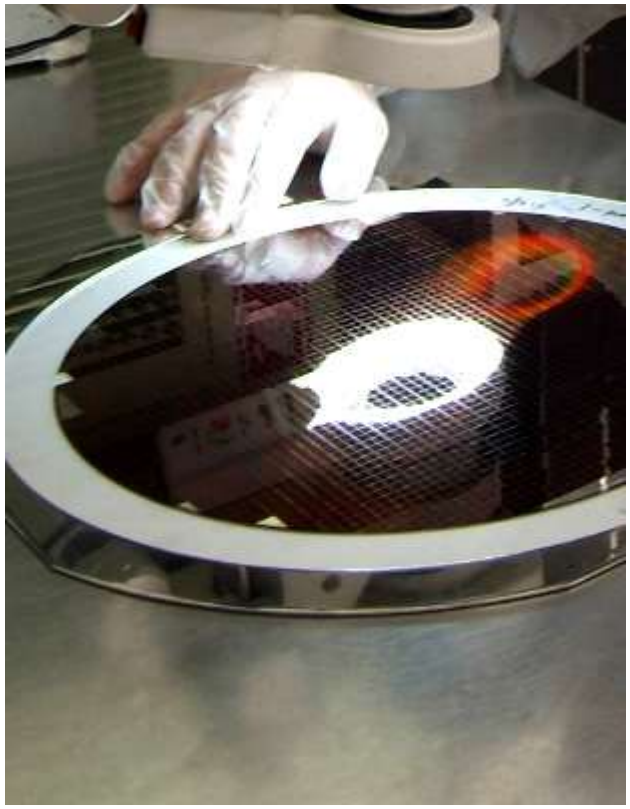
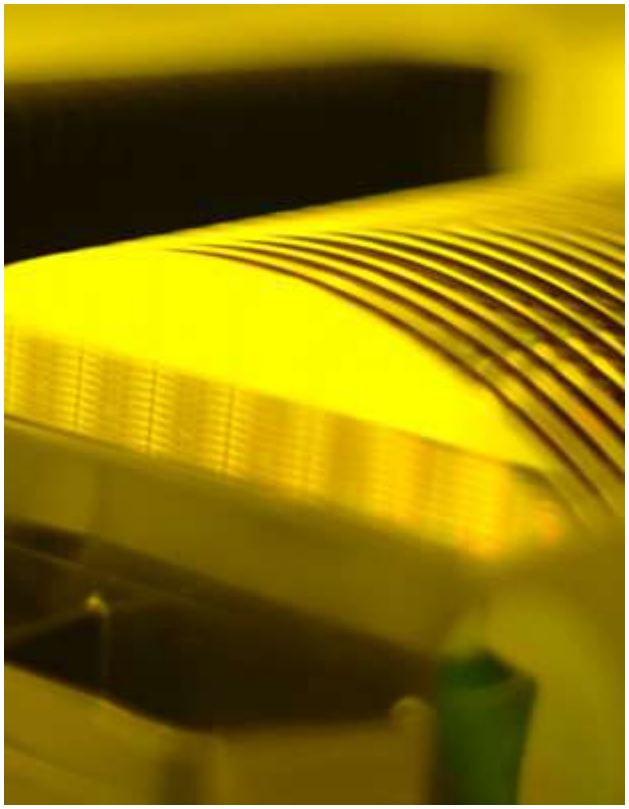




ChipMOS

# Industry Leading Provider of Outsourced Semiconductor Assembly, Test & Bumping Services

November 2026

# Safe Harbor Notice

- This presentation contains certain forward-looking statements. These forward-looking statements may be identified by words such as ‘believes,’ ‘expects,’ ‘anticipates,’ ‘projects,’ ‘intends,’ ‘should,’ ‘seeks,’ ‘estimates,’ ‘future’ or similar expressions or by discussion of, among other things, strategies, goals, plans or intentions. These statements may include financial projections and estimates and their underlying assumptions, statements regarding current macroeconomic conditions, including the impacts of high inflation, foreign exchange rates and risk of recession, on demand for our products, consumer confidence and financial markets generally; changes in trade regulations, policies, and agreements and the imposition of tariffs that affect our products or operations, including potential new tariffs that may be imposed and our ability to mitigate with respect to future operations, products and services, and statements regarding future performance. Actual results may differ materially in the future from those reflected in forward-looking statements contained in this document, based on a number of important factors and risks, which are more specifically identified in the Company’s most recent U.S. Securities and Exchange Commission (the “SEC”) filings. Further information regarding these risks, uncertainties and other factors are included in the Company’s most recent Annual Report on Form 20-F filed with the SEC and in its other filings with the SEC.

# Company Snapshot

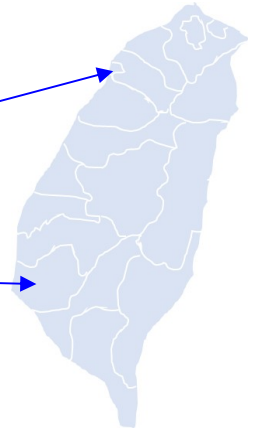
## Overview

- Founded : 1997
- Headquarter : Hsinchu, Taiwan
- Ticker Symbol : TWSE : 8150.TW
  NASDAQ : IMOS (ADS)
- Market Cap.[1]: 79,891.2MNTD
  (2,508.4MUSD[2])
- Employee[1]: 6,081

## Footprint

*Hsinchu: Memory /Mixed-signal test and Bumping*

*Tainan: Assembly and DDIC assembly & test*



## Key milestones

**2000**
- Started TCP package for LCD driver IC and 12" wafer assembly and testing business

**2014**
- Listed ChipMOS Taiwan on TWSE
- Invested in JMC and Ryowa

**2016**
- ChipMOS Taiwan merged ChipMOS Bermuda and issued ADS (Nasdaq Ticker: IMOS)

**2019**
- Awarded the Gold grade Award of the 1st National Enterprise Environmental Protection Award.

**2022**
- Honored 2022 National Sustainable Development Awards

**2023**
- Ranked top 5% of TWSE-listed companies for two consecutive years
- Disposed the entire remaining equity interests in Unimos

**2024**
- Honored Top 100 Exemplary Companies in Sustainability Award

**2025**
- Honored 2025 National Sustainable Development Awards
- Cumulative shipments of Auto panel DDICs have been more than 1,000Mea in 2025

(1) As of September 30, 2026
(2) The exchange rate was NT$31.85 against to US$1.00



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# ChipMOS Footprints

## Headquarter

Hsinchu Science Park, Hsinchu City



Hukou, Hsinchu County



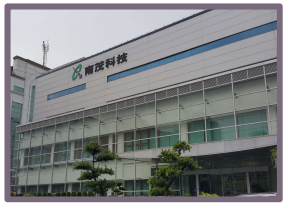
Memory & Mixed-signal Test

Memory Test

Zhubei II, Hsinchu County



Zhubei I, Hsinchu County



Wafer Bumping

Assembly & Memory Test

Southern Science Park, Tainan City









San Jose (Sale office)

ChipMOS U.S.A., Inc.



Shanghai (Sale office)

ChipMOS Semiconductors (Shanghai) LTD.



ChipMOS

# Positioned in Specialized OSAT Markets

- Providing turnkey solutions for niche OSAT markets
- Owning specialized teams and resources to support customer in the fields
- Growing with operation performance and strategic alliance including customers and suppliers

**Logic & Mixed Signal (1~3Q26: 9.5%)**

- Strategic business engagement
- #1 e-compass customer, technology transfer

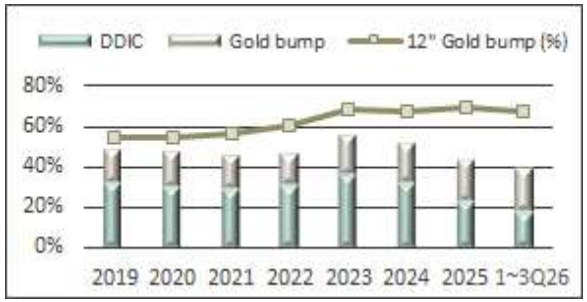
**Display Driver IC & Gold bump (1~3Q26: 39.7%)**

- Unique backend market
- High entry barrier
- Leverage with conventional backend resource

**Business Growth**

**Memory IC (1~3Q26: 50.8%)**

- Well cultivated customer base
- Wide solution & platform provider
- Continuous main stream product development




**Strategic Supplier/Partner**

- JMC (COF tape) /Ryowa (IC substrate)
  - ➢ Cash investment /Priority capacity
- Yoshikawakogyo (JP) /Globetronics (MY)
  - ➢ Overseas capacity leverage/collaboration






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# Business Operation Solutions for Customers





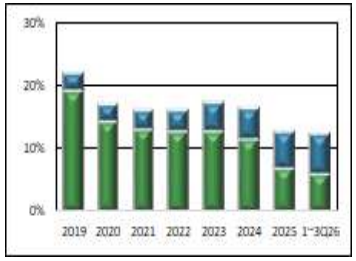

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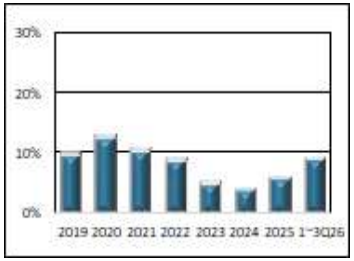
# Diversified Product Application

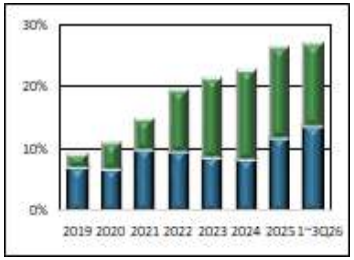
## Content Performance of 3Q26

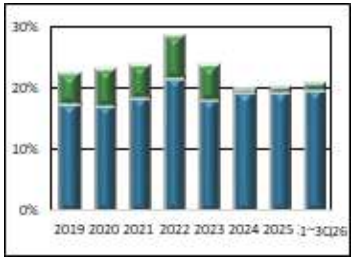
| Smart Mobile | TV | Computing | Auto/Industrial | Consumer |
|---|---|---|---|---|
| 31.2% | 11.1% | 8.6% | 27.7% | 21.4% |
| (QoQ +18.2%) | (QoQ +0.4% ) | (QoQ +52.1%) | (QoQ +8.1%) | (QoQ +9.2%) |
| ▪ Smart phone<br>▪ Wearable<br>▪ Watch, TWS | ▪ UHD/4K/8K TV<br>▪ OLED TV<br>▪ NB/Tablet | ▪ PC / Server<br>▪ SSD | ▪ In-car infotainment<br>▪ ADAS / sensor | ▪ Game, DSC, STB<br>▪ Smart speaker<br>▪ E-paper, Internet |




DDIC & Gold bump

Memory & Mixed-signal

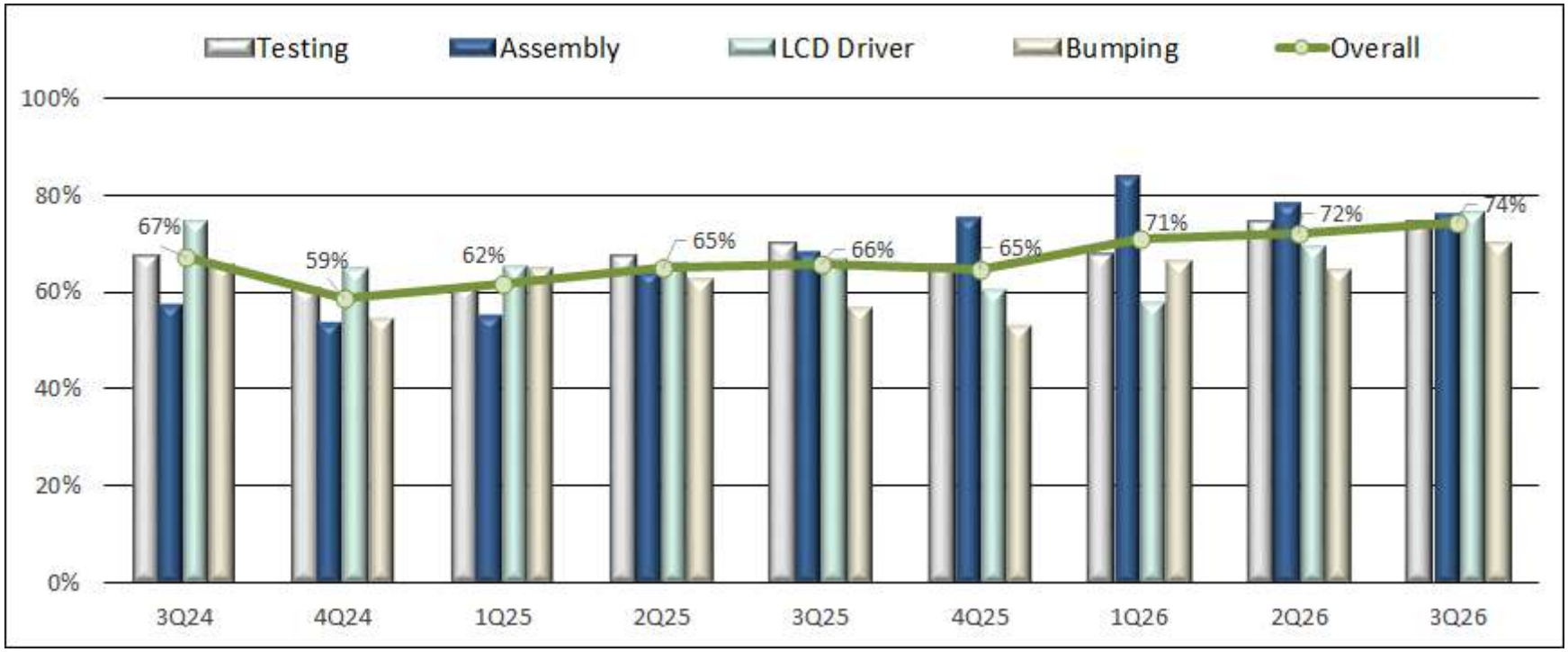
Note: Move “Watch” & “TWS” to “ Smart Mobile” from “Consumer” since 1Q24



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# Utilization

| Testing | Assembly | LCD Driver | Bumping | Overall |
|---|---|---|---|---|
| 3Q26: 74% | 3Q26: 76% | 3Q26: 77% | 3Q26: 70% | 3Q26: 74% |
| 2Q26: 74% | 2Q26: 78% | 2Q26: 69% | 2Q26: 65% | 2Q26: 72% |
| 3Q25: 70% | 3Q25: 68% | 3Q25: 67% | 3Q25: 57% | 3Q25: 66% |

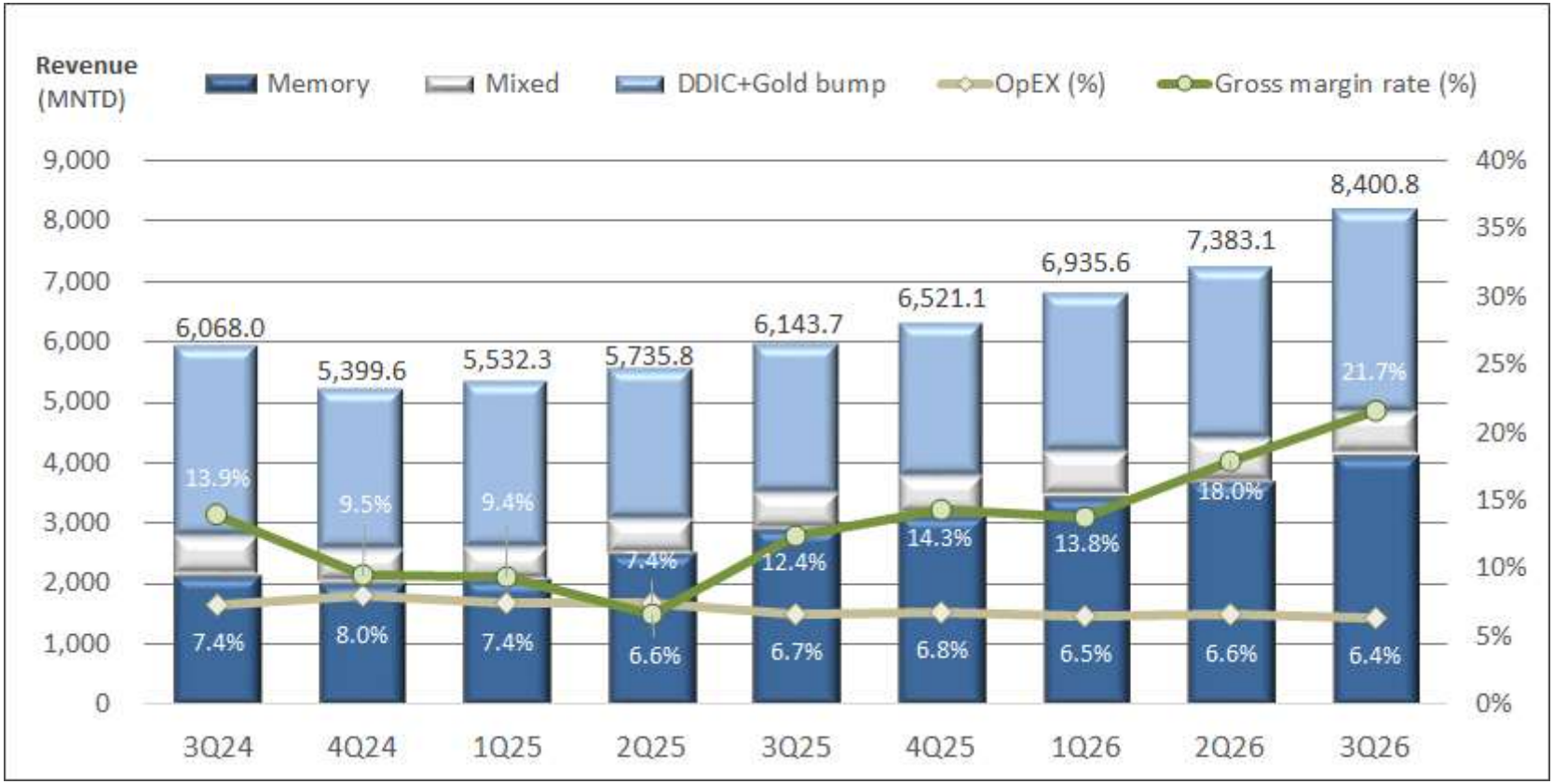





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# Quarterly Revenue & Gross Margin

- 3Q26
  - Revenue: NT$8,400.8M (QoQ: +13.8%, YoY: +36.7%)
  - Gross Margin: 21.7% (QoQ: +3.7ppts, YoY: +9.3ppts)

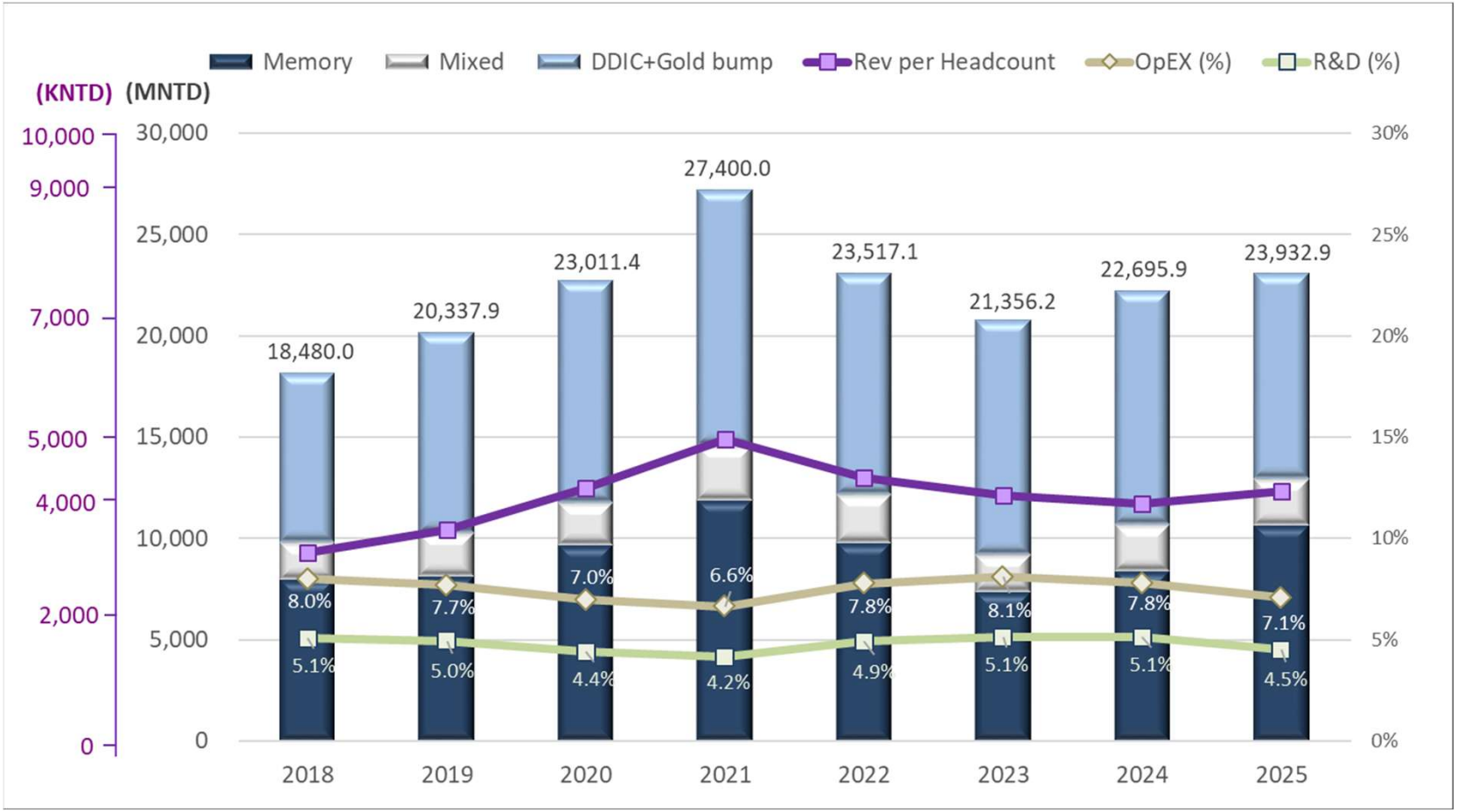





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# Reduce OpEx & Maintain R&D

- OpEx: Reduce from 9.4% (2016) to 6.4% (3Q26)
- R&D: Maintain 4.2~5.1%

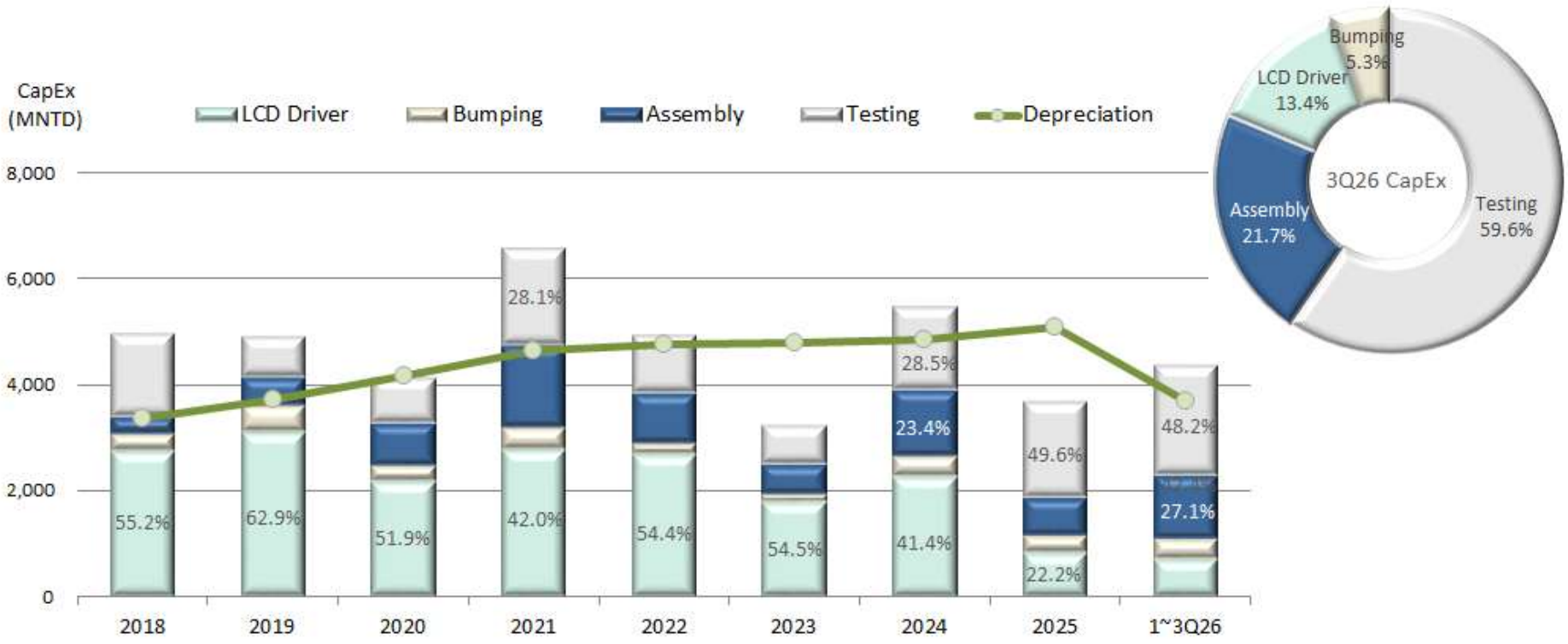





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# CapEx & Depreciation

- 3Q26
  - CapEx: NT$1,455.4M
  - Depreciation: NT$1,228.4M

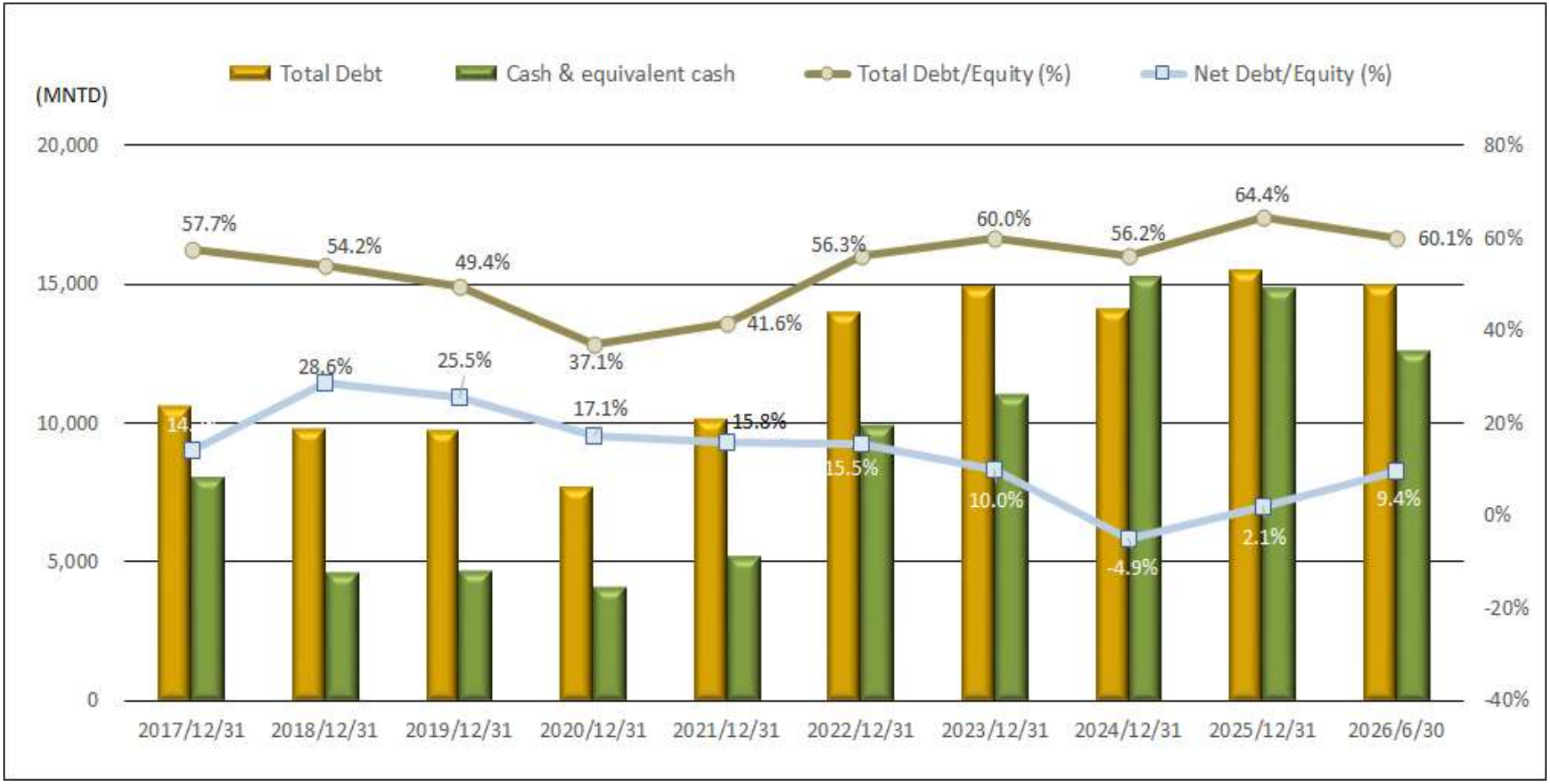





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# Healthy Debt and Cash Level

- ~20.3BNTD of Cash & equivalent cash and Unused credit lines up to Sep/30'26



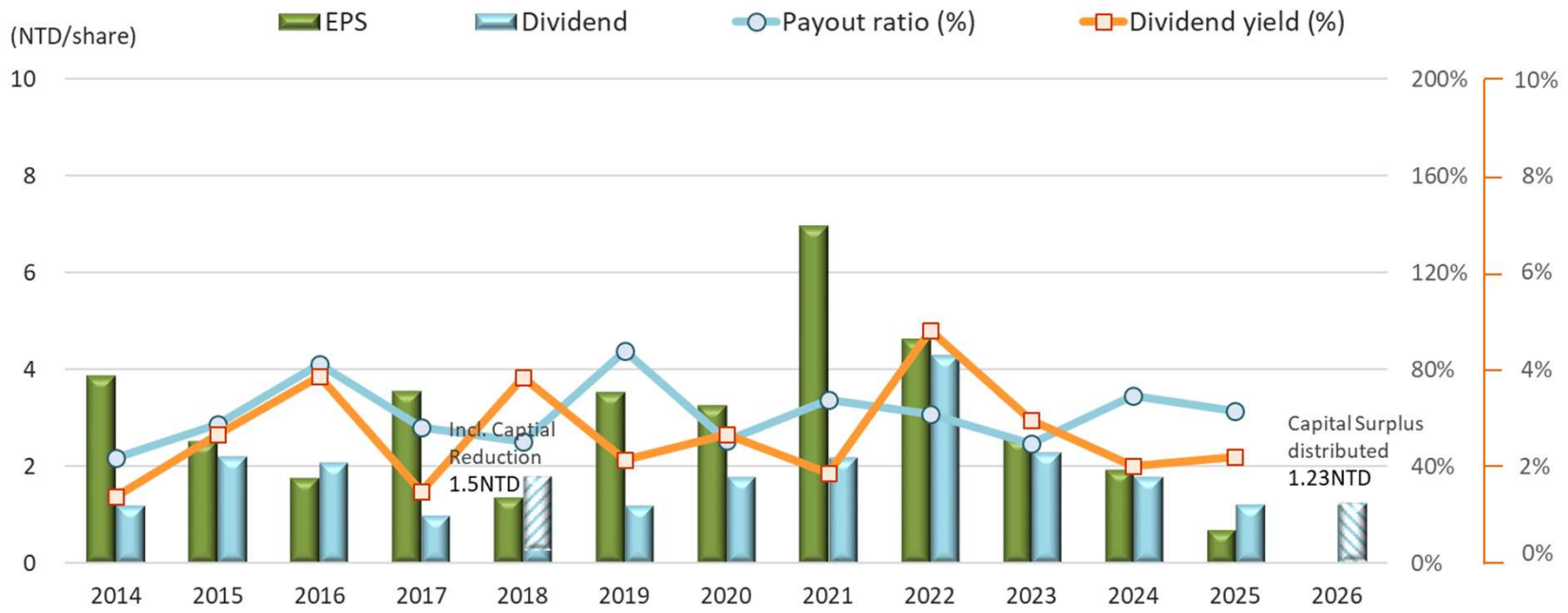

*Note: Total debt to Equity = (ST loan + LT loan)/ Equity*



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# Stable Payout and High Dividend Yield

- EPS: 1.89NTD (3Q26), 3.89NTD (1~3Q26)
- Payout ratio (2014~2024):  average: > 60%
  - 2026: distributed1.23NTD by Capital Surplus
- Dividend yield (2014~2025): average: ~5.3%
- ~10.5BNTD of unappropriated retained earnings up to Sep/30'26




*Note: 2019 Payout ratio = 2019 Dividend /2018 EPS*

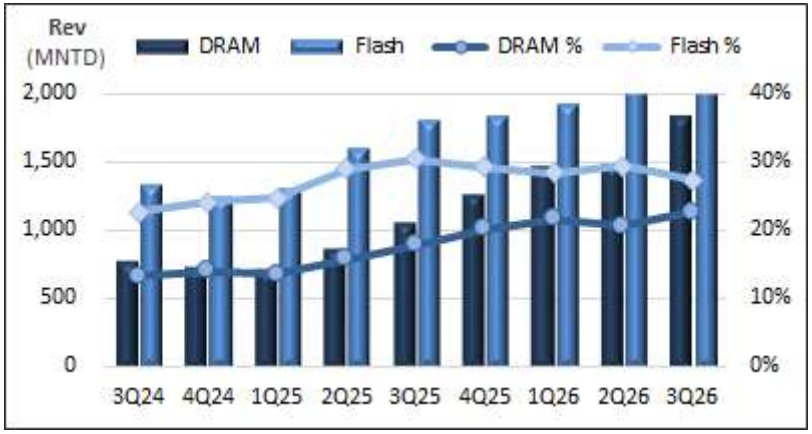


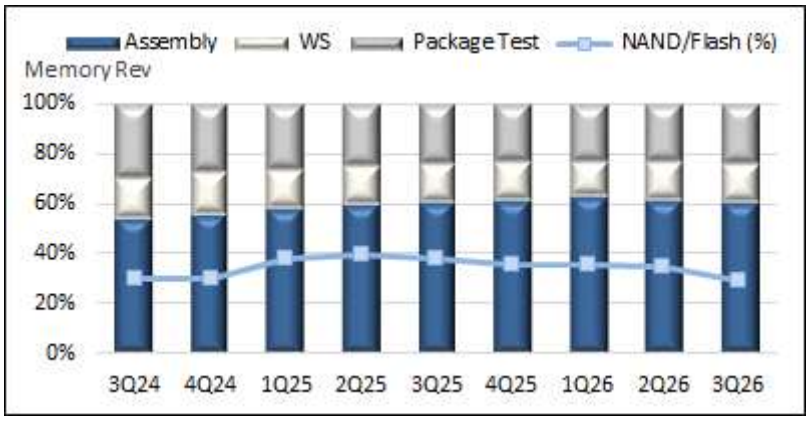
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# Operation Performance

## Memory IC

**3Q26 : 50.6%**




## Key Message

- ❑ QoQ +12.2%, YoY +42.0%
  - ■ DRAM: 22.6% (QoQ +23.9%)
    - ✓ Niche DRAM QoQ +10.1%
  - ■ Flash: 27.4% (QoQ +5.0%)
    - ✓ NAND represented about 29.3% of 3Q Flash revenue, (QoQ -11.1%)
    - ✓ NOR QoQ +10.5%
- ❑ Momentum expected to be better than DDIC
  - ■ DRAM demand continues to exceed supply
  - ■ Flash momentum rebound

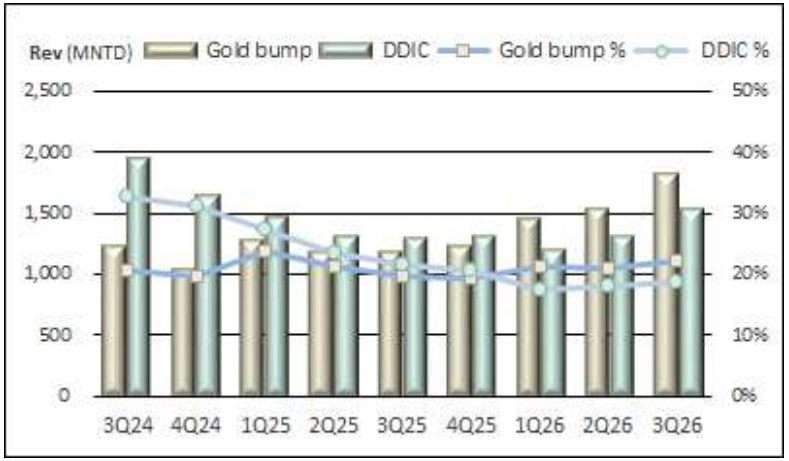


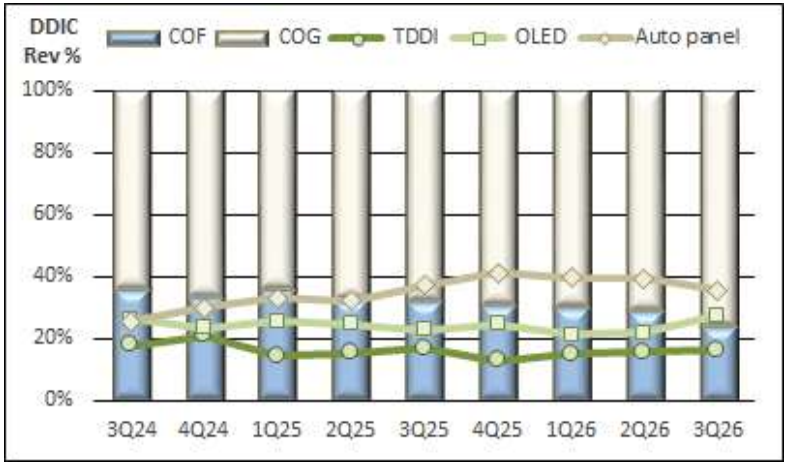
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# Operation Performance (Cont'd)

## DDIC & Gold bump

**3Q26: 40.9%**




## Key Message

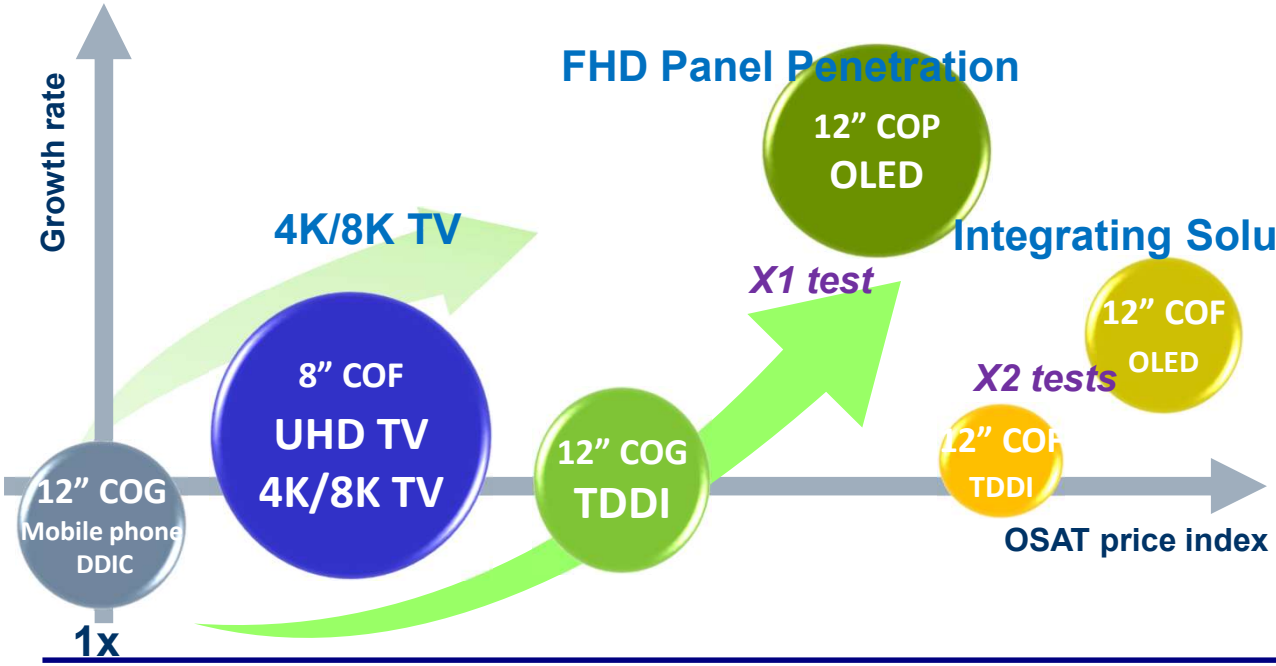
- ❑ QoQ +18.2%, YoY +35.7%
  - ■ Around 35.6% DDIC revenue is coming from Automotive application in 3Q (QoQ +5.8%)
  - ■ OLED: Represented about 27.4% of 3Q DDIC revenue (QoQ +46.0%)
- ❑ Consumer end-demand impacted by high memory product price
- ❑ Momentum balanced led by seasonal re-stocking
  - ■ OLED momentum benefitting from seasonal re-stocking



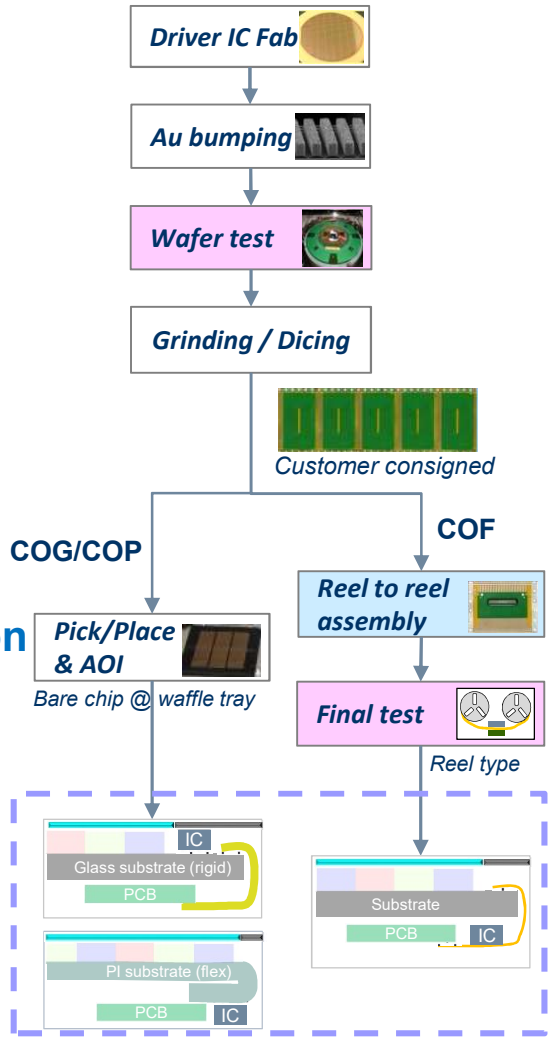
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# Leverage DDIC Growth by Higher ASP Product Penetration

- **Quantity increase**
  - TV: 8K TV emerging; more DDIC quantity consumption
- **Longer test time**
  - TDDI: **~3x** wafer testing time
  - OLED: **Longer testing time + high end test platform**
  - Automotive panel: **+ negative temp test procedure**
- **COF: X2 test procedure** (wafer sort + Final test)
  **Integrating** more functions **solution**



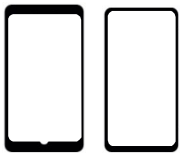
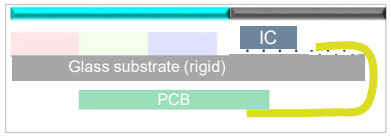
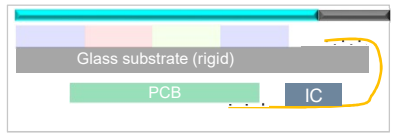
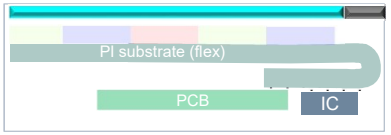
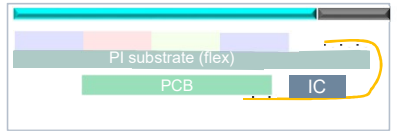
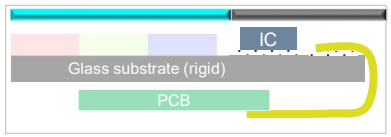
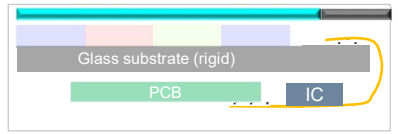

## DDIC OSAT Flow






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# Display Driver IC vs Panel Comparison

| | Bare chip (COG/COP) | | Reel format (COF) |
|---|---|---|---|
| Small panel (Smart Phone)  |  12” COG (DDIC/TDDI) | Narrow bezel |  12” COF (TDDI) |
| |  12” COP (OLED) | |  12” COF (OLED) |
| Middle panel (Tablet/NB)  |  COG | Slim border |  COF |
| Large panel (4K/8K TV)  | | |  COF (DDIC/OLED) |

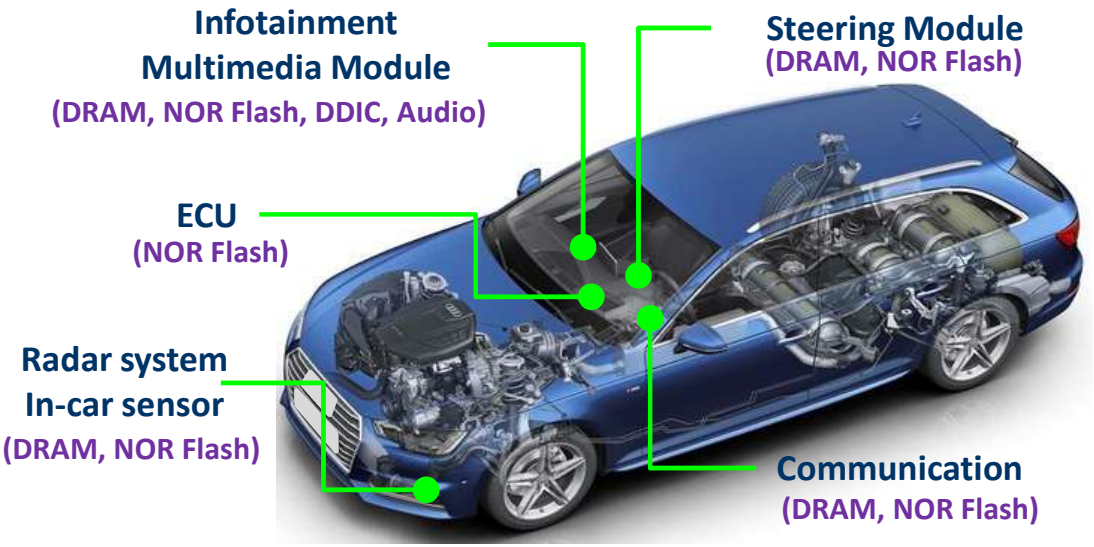





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# Recognized Capability in Automotive Application

- ✓ Qualified by **10 of top 15 Tier 1** automotive electronic component suppliers
- ✓ More than **1,270 Mea** Auto panel DDIC since 2019




BOSCH Invented for life · ZF · DENSO Crafting the Core · HYUNDAI MOBIS · CATL 宁德时代 · AISIN · Continental · Valeo la Qualité d'Origine · SUMITOMO ELECTRIC Connect with Innovation · APTIV

*Qualified 10 of Top 15 Tier 1*

Panasonic AUTOMOTIVE · JTEKT · Visteon · MITSUBISHI ELECTRIC Changes for the Better · DRÄXLMAIER · LG Innotek · TENNECO · HARMAN A SAMSUNG COMPANY · BMW · Hitachi Astemo · MARELLI · TOSHIBA · Hirschmann Car Communication · DESAY SV · KYOCERA The ECOLaser Printer. · KOSTAL · NIPPON SEIKI · YAMAHA · Murakami · NLT NEXT LEVEL TECHNOLOGY

*Other qualified automotive electronic component suppliers*



ChipMOS

# ChipMOS ESG Performance

## Environmental 環境面

國家企業環保獎金級獎
暨 榮譽環保企業獎座

Gold grade of National Enterprise Environmental Protection Award & Honorary Environmental Protection Enterprise Award

- ✓ **Renewable energy**
  (Solar energy generation)
  **59,591**戶家庭每月用電量
  114年再生能源(太陽能)累計發電數
- ✓ **Water resource recycle**
  (Process recycling water)
  **6,136**座國際標準泳池
  18年來製程回收水成果
- ✓ **CDP**
  **Climate Change: B**
  **Water Resource: A**

## Social 社會面

人才發展品質管理系統
銀牌(TTQS)

Silver grade of Talent Quality-Management System (TTQS)

- ✓ **Excellent Gender Equality in Employment**
- ✓ **100% 遵循RBA人權規範**
  100% follow RBA
  Hsinchu & Chupei I award "Platinum" Grade of RBA VAP audit result
- ✓ **社區參與 Social Engagement**
  **22,630**人次 2025年投入志工
  22,630 attendees for Volunteer Works

## Governance 治理面

**114年二度榮獲國家永續發展獎**
2025 National Sustainable Development Awards for the second time

第八、九屆公司治理評鑑 上市公司前5%

Ranked top 5% of TWSE-listed companies for two consecutive years

- ✓ **Board of Directors**
  **Independent Director 56%**
  **Female Director 2** seats
  **獨立董事過半；女性董事 2席**
- ✓ **Sustainable Value Creation**
  連續 **8年** 榮獲TCSA台灣永續獎
  Awarded TCSA Corporate Sustainability for 8 consecutive years

*Please visit ChipMOS web site to get more ESG results information, https://https://www.chipmos.com/english/csr/report.aspx*

# Sustainability (SDGs ) Approach

## 綠色營運，邁向低碳轉型
Green Manufacturing

- 致力推動綠色生產
  Green manufacturing
- 持續投入與評估綠色能源
  Green energy
- 攜手供應鏈同行
  Sustainable supply chain

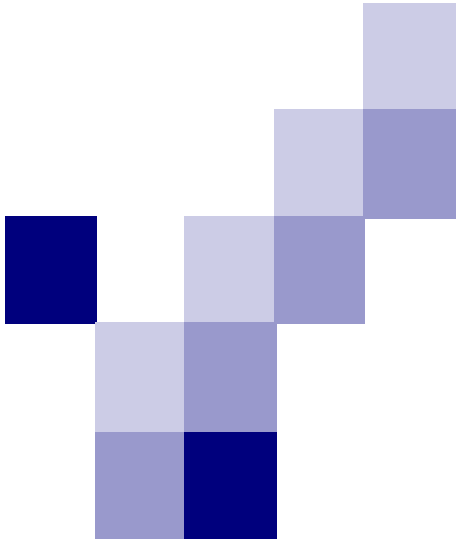



## 多元共融，共創永續未來
Diversity & Inclusive Workplace

- 落實RBA準則管理
  Conform RBA's conducts standard
- 重視人才發展培育
  Talent Development and Cultivation
- 持續社會參與
  Continuously social engagement

## 穩健治理，提升組織韌性
Robust Governance

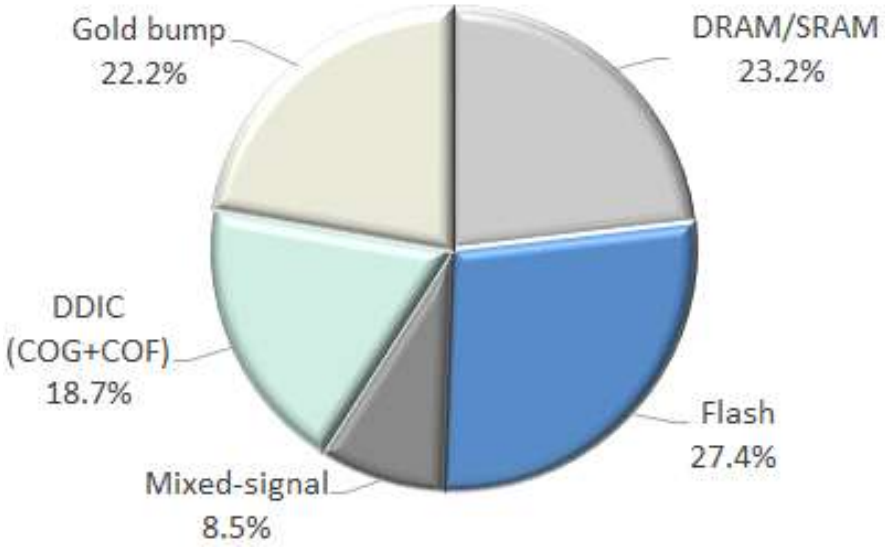
- 持續提升公司治理　Continuously enhance governance
- 與客戶長期合作夥伴關係
  Long term partner ship & cooperation with customer

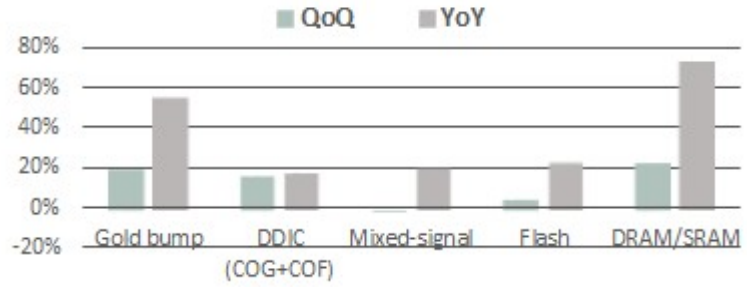


# 3Q26 Financial Results

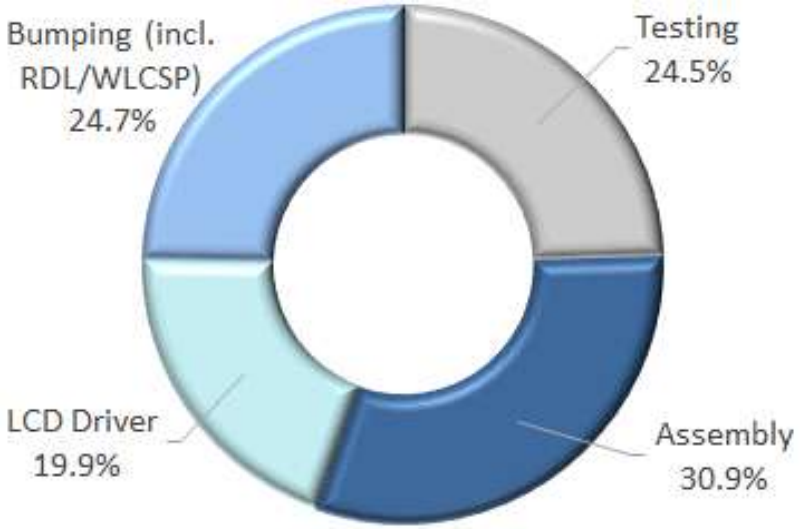
# 3Q26 Revenue Breakdown

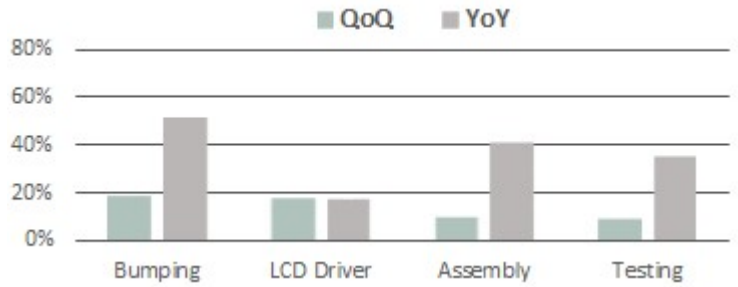
## Product




## Manufacturing Site






ChipMOS

# Consolidated Operating Results Summary

| (NT$ Millions) | 3Q26 | 2Q26 | 3Q25 |
|---|---|---|---|
| **Revenue** | **8,400.8** | **7,383.1** | **6,143.7** |
| Profit Attributable to the Company | 1,323.3 | 891.7 | 352.2 |
| **EPS Attributable to the Company - Basic (NT$)** | **1.89** | **1.28** | **0.50** |
| Earnings per ADS equivalent - Basic (US$)(1) | 1.19 | 0.80 | 0.31 |
| **Depreciation & Amortization** | **1,228.4** | **1,218.1** | **1,266.5** |
| CapEx | 1,455.4 | 2,380.2 | 796.7 |
| **Return on Equity (%)(2)** | **20.8%** | **14.4%** | **6.0%** |

Notes:
(1) The exchange rate was NT$31.85 against to US$1.00
(2) Annualized return on equity to the Company for the quarter

# Consolidated Statements of Comprehensive Income

| (NT$ Millions) | 3Q26 | 2Q26 | QoQ | 3Q25 | YoY |
|---|---|---|---|---|---|
| Revenue | 8,400.8 | 7,383.1 | 13.8% | 6,143.7 | 36.7% |
| Gross Profit | 1,820.5 | 1,325.6 | 37.3% | 759.7 | 139.6% |
| **Gross Margin** | **21.7%** | **18.0%** | **3.7ppts** | **12.4%** | **9.3ppts** |
| Operating Expenses | (536.6) | (486.5) | 10.3% | (410.2) | 30.8% |
| Operating Profit | 1,657.3 | 948.0 | 74.8% | 369.9 | 348.0% |
| **Operating Profit Margin** | **19.7%** | **12.8%** | **6.9ppts** | **6.0%** | **13.7ppts** |
| Non-operating Income (Expenses) (1) | (29.7) | 78.9 | -137.6% | 68.5 | -143.4% |
| Profit Attributable to the Company | 1,323.3 | 891.7 | 48.4% | 352.2 | 275.7% |
| **EPS Attributable to the Company - Basic (NT$)** | **1.89** | **1.28** | **47.7%** | **0.50** | **278.0%** |
| Weighted Average Shares Outstanding (in thousands) - Basic | 699,983 | 699,983 | | 706,736 | |
| EPS Attributable to the Company - Diluted (NT$) | 1.89 | 1.27 | 48.8% | 0.50 | 278.0% |
| Weighted Average Shares Outstanding (in thousands) - Diluted | 701,566 | 701,131 | | 706,736 | |

Note (1) :
QoQ: Difference mainly due to the adverse impact on valuation of financial assets at fair value through profit or loss of NT$89M from the gain on valuation of financial assets at fair value through profit or loss of NT$78M in 2Q26 to loss on valuation of financial assets at fair value through profit or loss of NT$11M in 3Q26 and the gain on disposal of investments accounted for using equity method of NT$14M in 2Q26.
YoY: Difference mainly due to the adverse impact on foreign exchange of NT$102M from foreign exchange gains of NT$84M in 3Q25 to foreign exchange losses of NT$18M in 3Q26.

# Consolidated Statements of Financial Position & Key Indices

| (NT$ Millions) | 3Q26 Amount | 3Q26 % | 2Q26 Amount | 2Q26 % | 3Q25 Amount | 3Q25 % |
|---|---|---|---|---|---|---|
| Current Assets | 24,277.4 | 53.2% | 25,573.0 | 54.5% | 23,067.2 | 53.7% |
| Non-current Assets | 21,352.7 | 46.8% | 21,391.2 | 45.5% | 19,878.4 | 46.3% |
| **Total Assets** | **45,630.1** | **100.0%** | **46,964.2** | **100.0%** | **42,945.6** | **100.0%** |
| Current Liabilities | 8,747.3 | 19.2% | 10,716.5 | 22.8% | 9,324.2 | 21.7% |
| Non-current Liabilities | 10,765.6 | 23.6% | 11,397.6 | 24.3% | 10,250.2 | 23.9% |
| **Total Liabilities** | **19,512.9** | **42.8%** | **22,114.1** | **47.1%** | **19,574.4** | **45.6%** |
| Total Equity | 26,117.2 | 57.2% | 24,850.1 | 52.9% | 23,371.2 | 54.4% |
| **Total Liabilities and Equity** | **45,630.1** | **100.0%** | **46,964.2** | **100.0%** | **42,945.6** | **100.0%** |
| | | | | | | |
| **Key Indices** | | | | | | |
| A/R Turnover Days | 81 | | 85 | | 88 | |
| Inventory Turnover Days | 69 | | 70 | | 55 | |

# Consolidated Statements of Cash Flows

| (NT$ Millions) | 1Q-3Q26 | 1Q-3Q25 |
|---|---|---|
| **Cash and Cash Equivalents at Beginning of Period** | **14,858.9** | **15,219.0** |
| Net Cash Generated from (used in) Operating Activities | 2,718.3 | 2,105.7 |
| Net Cash Generated from (used in) Investing Activities | (4,139.2) | (2,961.7) |
| Net Cash Generated from (used in) Financing Activities | (3,516.4) | (1,368.5) |
| Effect of Exchange Rate Change on Cash | 4.1 | (17.5) |
| **Cash and Cash Equivalents at End of Period** | **9,925.7** | **12,977.0** |
| | | |
| **Free Cash Flow[(1)(2)]** | **975.6** | **1,520.5** |

Notes :

(1) Free cash flow was calculated by adding depreciation, amortization, interest income together with operating profit and then subtracting CapEx, interest expense, income tax expense and dividend from the sum.

(2) Difference mainly due to the increase of CapEx of NT$2,415M, the income tax change of NT$553M from the income tax benefit of NT$20M in 1Q-3Q25 to income tax expense of NT$533M in 1Q-3Q26, the decrease of depreciation expenses of NT$163M and partially offset by the increase of operating profit of NT$2,618M.

# Company Website

**www.chipmos.com**